Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L10	6110	probe same ((substrate material $5film coat$3 layer sheet pad wafer film lamina level plane) with silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:10
L11	5611	l10 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:10
L12	559	l11 and ((non$1conduct$5 dielectric insulat$5 isolat$5) adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)) with ((silicon adj nitride) (silicon adj oxide))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:11
L13	7	l12 and ((project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment)) with (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:12
L14	2736	probe with ((substrate material $5film coat$3 layer sheet pad wafer film lamina level plane) with silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:16
L15	2541	l14 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 11:43
L16	248	l15 and ((non$1conduct$5 dielectric insulat$5 isolat$5) adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)) with ((silicon adj nitride) (silicon adj oxide))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:17

L17	5	l16 and ((project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment)) with (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:20
L18	2403	probe with ((substrate material $5film coat$3 layer sheet pad wafer film lamina level plane) near5 silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:16
L19	2237	l18 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:17
L20	184	l19 and ((non$1conduct$5 dielectric insulat$5 isolat$5) adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)) near5 ((silicon adj nitride) (silicon adj oxide))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:18
L21	5	l20 and ((project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment)) with thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:20
L22	155776	probe same (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 11:42
L23	143412	l22 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 11:43

L25	61	l23 and ((project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment)) same (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3)) same thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:04
L27	5	l25 and (project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment) near3 thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:29
L29	2	l25 and conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3) near3 thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:29
L30	5647	(324/751,752,754,755,757,758.ccls.) and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 12:40
L31	8919	(324/72.5,715,765,158.1.ccls.) and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 12:41
L32	395	(324/437,445-447.ccls.) and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 12:42
L33	624	(324/690,696.ccls.) and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 12:42

L34	12	I30 and (project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment) near3 thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 12:45
L35	11	I31 and (project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment) near3 thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:01
L36	0	I32 and (project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment) near3 thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 12:45
L37	0	I33 and (project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment) near3 thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 12:45
L38	58	I23 and pitch near3 (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:10
L39	1	I23 and (pitch near3 (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))) with micron	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:06
L40	1	I23 and (pitch near3 (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))) same micron	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:17

L41	1	l23 and (pitch near3 (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))) same micro$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:20
L42	226	l23 and (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3)) same thickness same width	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:23
L43	6	l25 and (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3)) same thickness same width	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:24
L44	75	l23 and conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3) near3 thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 14:28
L45	0	l44 and (project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment) near3 thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:30
L46	9	l44 and (project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment) same thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 13:30
L47	7	l23 and (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3) near5 thickness) same (nano$1meter "nm")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 14:59

L48	1	l23 and (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3) near5 pitch) same micro$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 15:08
L49	24	l23 and (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3)) same pitch same micro$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 15:15
L50	6	(conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3)) same (pitch near3 (("a" one "1") adj micro$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 15:17
L51	5	(conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3)) with (pitch near3 (("a" one "1") adj micro$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 15:18
L52	6	l50 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 15:20
L53	5	l51 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 15:19
S1	181	(324/724.ccls.) and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 16:44

S2	419	(324/722,691.ccls.) and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 15:18
S3	242	(324/649,600.ccls.) and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 12:39
S4	80	S1 and probe same (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 09:46
S5	55	S2 and probe same (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 14:44
S6	17	S3 and probe same (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 14:44
S7	17	S4 and (project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 09:42
S8	6	S5 and (project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 16:27

S9	2	S6 and (project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 16:26
S10	1	S7 and ((project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment)) same (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 09:52
S11	10	S7 and (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 15:05
S12	10	S7 and (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 15:07
S13	3	S8 and (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/16 16:12
S14	17361	((non$1conduct$5 dielectric insulat$5) adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)) with ((project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 09:48
S15	16524	S14 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 09:50

S16	477	S15 and probe same (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 11:42
S17	110	S16 and ((project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment)) same (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 11:44
S18	70	S16 and ((project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment)) with (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 09:56
S19	16	S18 and (plural$5 number multipl$5 series several set) adj2 (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 09:57
S20	17363	((non$1conduct$5 dielectric insulat$5) adj (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)) with ((project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 09:58
S21	16526	S20 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/21 14:25
S22	477	S21 and probe same (substrate material $5film coat$3 layer sheet pad wafer film lamina level plane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/21 14:25

S23	70	S22 and ((project$5 protrud$5 extend$5) near2 (portion part member moiety parcel piece section segment)) with (conduct$5 near2 (wir$3 cord$3 cabl$3 line link channel connect$5 lead$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:01
S24	2	Kenan near2 gad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/21 15:50